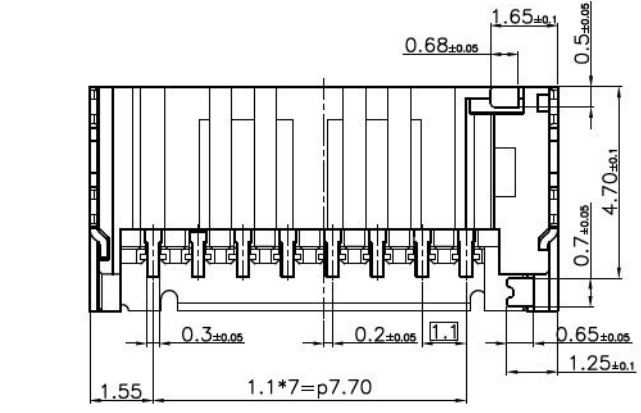
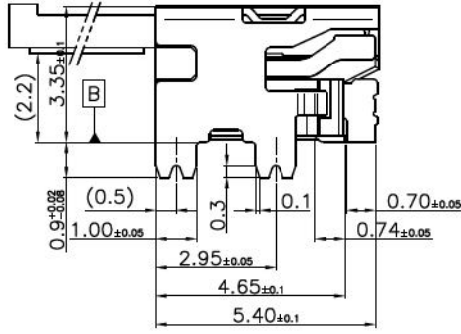
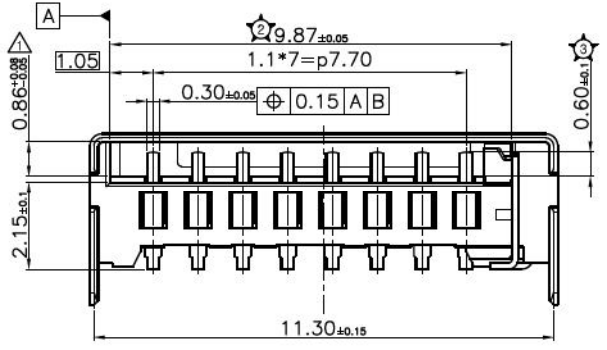
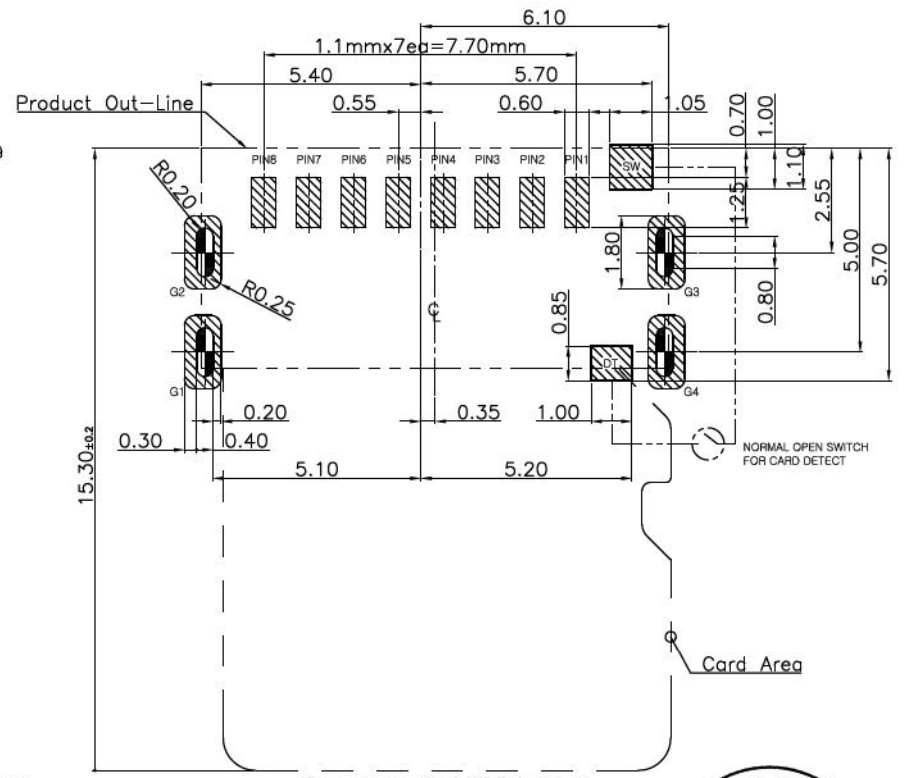
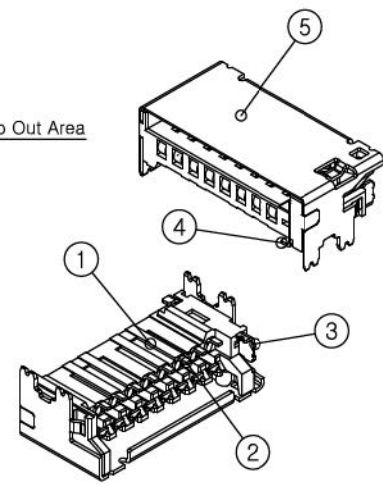
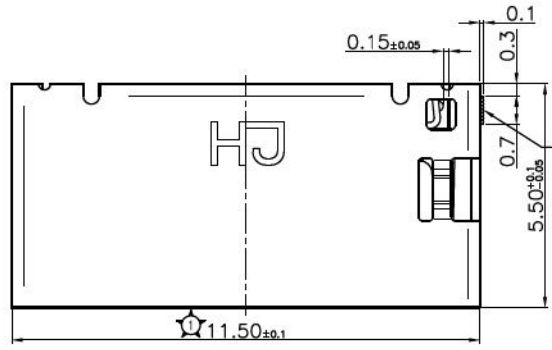


Rev No.	Description of Revision	Date	Name	Approved	ECN No.
△X 1	SPEC 오기 수정	2011.09.15	J.S. Kim		



- ※ NOTE
1. PLATING (Reel to Reel 방식)
 - 1) Contact (Jig Plating)
 - Contact Area : Au 0.2μm Min. over Ni 1.25~5.5μm
 - Lead Area : Au 0.05μm Min. over Ni 1.25~5.5μm
 - 2) Switch, Detect (Dipping Plating)
 - Contact Area : Au 0.1μm Min. over Ni 1.25~5.5μm
 - Lead Area : Au 0.05μm Min. over Ni 1.25~5.5μm
 - 3) Metal Shell : Ni 1.25~3.0μm (Dipping Plating)
 2. ☆ : C.T.Q
 3. Coplanarity : 0.08Max.

Recommended PCB Layout
(General Tolerance : ±0.05)



5	METAL SHELL	Stainless Steel	Note. 1	t0.2
4	DETECT	P-Bronze	Note. 1	t0.15
3	SWITCH	P-Bronze	Note. 1	t0.15
2	CONTACT	P-Bronze	Note. 1	t0.15
1	HOUSING	LCP	Black Color	UL94V-0
No	Descriptions	Material	Finish	Remarks
General Tolerance		Scale N/S	Units mm	Sheet
Dimension		Date 2011.07.08	1 of 1	
X	± 0.2	Drawn	Design	Checked
X.X	± 0.1	Reviewed	Approved	
X.XX	± 0.05	J.S. Kim		
X.XXX	± 0.01	- 01/22 H		
ANGLE	± 1°	HJ&C HYUP JIN I&C CO., LTD.		
TITLE				Rev.
HD08-AL0335				
Micro SD Socket				
Customer Drawing				
SW No.				
DWG No. HD08-AL0335-A1				1